

# US Patent & Trademark Office

## Patent Public Search | Text View

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United States Patent	12394733
Kind Code	B2
Date of Patent	August 19, 2025
Inventor(s)	Noori; Basim et al.

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### Stacked RF circuit topology

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#### Abstract

An integrated circuit device package includes a substrate, a first die comprising active electronic components attached to the substrate, and package leads configured to conduct electrical signals between the first die and an external device. At least one integrated interconnect structure is provided on the first die opposite the substrate. The at least one integrated interconnect structure extends from the first die to an adjacent die attached to the substrate and/or to at least one of the package leads, and provides electrical connection therebetween. Related devices and power amplifier circuits are also discussed.

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**Appl. No.:** 17/210660

**Filed:** March 24, 2021

#### Prior Publication Data

Document Identifier	Publication Date
US 20210313284 A1	Oct. 07, 2021

#### Related U.S. Application Data

us-provisional-application US 63004760 20200403

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#### Publication Classification

**Int. Cl.:** H01L23/66 (20060101); H01L23/538 (20060101); H01L25/065 (20230101); H03F3/193 (20060101); H03F3/195 (20060101); H03F3/213 (20060101); H10D62/832 (20250101); H10D62/85 (20250101)

**U.S. Cl.:**

**CPC** H01L23/66 (20130101); H01L23/5386 (20130101); H01L25/0657 (20130101); H03F3/193 (20130101); H03F3/195 (20130101); H03F3/213 (20130101); H10D62/8325 (20250101); H10D62/8503 (20250101);

## Field of Classification Search

**CPC:** H01L (25/0657); H01L (25/0652); H01L (25/043); H01L (25/071); H01L (25/074); H01L (25/0756); H01L (25/112); H01L (25/117); H01L (2224/08145); H01L (27/0688); H01L (23/49827); H01L (23/5384); H01L (23/481); H01L (29/4175); H01L (2225/06541-06544); H01L (2225/06548); H01L (21/76898); H03F (3/139); H03F (3/195); H03F (3/213); H03F (3/2171)

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## References Cited

### U.S. PATENT DOCUMENTS

Patent No.	Issued Date	Patentee Name	U.S. Cl.	CPC
3969745	12/1975	Blocker	N/A	N/A
6586833	12/2002	Baliga	257/691	H10D 30/0291
9786660	12/2016	Farrell et al.	N/A	N/A
9807882	12/2016	Berdy et al.	N/A	N/A
10438894	12/2018	Farooq et al.	N/A	N/A
10855244	12/2019	Trang et al.	N/A	N/A
11114988	12/2020	Kim et al.	N/A	N/A
11521957	12/2021	Lee	N/A	N/A
11557539	12/2022	Romanczyk et al.	N/A	N/A
11587852	12/2022	Shilimkar et al.	N/A	N/A
11652461	12/2022	Trang et al.	N/A	N/A
11735538	12/2022	Radulescu	N/A	N/A
2002/0179945	12/2001	Sakamoto et al.	N/A	N/A
2003/0062541	12/2002	Warner	257/E23.092	H01L 24/50
2004/0238857	12/2003	Beroz	257/E23.092	H01L 23/49822
2008/0099800	12/2007	Miller	257/738	H01L 23/66
2009/0020848	12/2008	Ono et al.	N/A	N/A
2009/0091011	12/2008	Das et al.	N/A	N/A
2010/0109052	12/2009	Nakajima et al.	N/A	N/A
2011/0215472	12/2010	Chandrasekaran	257/737	H01L 24/73
2011/0304013	12/2010	Chen et al.	N/A	N/A
2011/0309372	12/2010	Xin et al.	N/A	N/A
2012/0018892	12/2011	Soltan	N/A	N/A
2012/0086497	12/2011	Vorhaus	N/A	N/A
2012/0299178	12/2011	Kanaya et al.	N/A	N/A

2013/0168854	12/2012	Karikalan et al.	N/A	N/A
2014/0014969	12/2013	Kunii et al.	N/A	N/A
2014/0054604	12/2013	Ritenour	N/A	N/A
2014/0159118	12/2013	Lenci et al.	N/A	N/A
2014/0184357	12/2013	Jang	N/A	N/A
2014/0239411	12/2013	Brech et al.	N/A	N/A
2014/0312458	12/2013	Ashrafzadeh et al.	N/A	N/A
2015/0171015	12/2014	Mahajan	257/774	H01L 23/3114
2015/0171080	12/2014	Vorhaus	N/A	N/A
2016/0087586	12/2015	Szymanowski	330/250	H01L 24/49
2016/0285418	12/2015	Jones et al.	N/A	N/A
2017/0025349	12/2016	Wood	N/A	N/A
2017/0053909	12/2016	Laighton et al.	N/A	N/A
2017/0062319	12/2016	Guo et al.	N/A	N/A
2017/0085228	12/2016	Abdo et al.	N/A	N/A
2017/0110451	12/2016	Fraser et al.	N/A	N/A
2017/0294528	12/2016	Ren et al.	N/A	N/A
2018/0138132	12/2017	Nishizawa et al.	N/A	N/A
2019/0088607	12/2018	Wang et al.	N/A	N/A
2019/0097001	12/2018	Laroche et al.	N/A	N/A
2019/0131273	12/2018	Chen et al.	N/A	N/A
2019/0148276	12/2018	Chen	257/774	H01L 21/563
2019/0199289	12/2018	Wei et al.	N/A	N/A
2019/0304913	12/2018	Wu	N/A	H01L 23/5384
2019/0304952	12/2018	Weis	N/A	H01L 24/16
2019/0356274	12/2018	Zhu et al.	N/A	N/A
2020/0043946	12/2019	Paul et al.	N/A	N/A
2020/0105741	12/2019	Lin et al.	N/A	N/A
2020/0118922	12/2019	Hill	N/A	N/A
2020/0135766	12/2019	Dutta et al.	N/A	N/A
2020/0168602	12/2019	Kojima et al.	N/A	N/A
2020/0287536	12/2019	Udrea et al.	N/A	N/A
2020/0373892	12/2019	Kim et al.	N/A	N/A
2021/0098408	12/2020	Ting	N/A	H01L 23/49816
2021/0151428	12/2020	Dutta et al.	N/A	N/A
2021/0167199	12/2020	Sriram et al.	N/A	N/A
2021/0202408	12/2020	Khalil et al.	N/A	N/A
2021/0257472	12/2020	Sato et al.	N/A	N/A
2021/0313285	12/2020	Noori et al.	N/A	N/A
2021/0313935	12/2020	Noori et al.	N/A	N/A
2021/0398971	12/2020	Som et al.	N/A	N/A
2022/0020874	12/2021	Fisher et al.	N/A	N/A
2022/0044986	12/2021	Khalil et al.	N/A	N/A
2022/0190126	12/2021	Kabir et al.	N/A	N/A
2023/0075505	12/2022	Radulescu et al.	N/A	N/A
2023/0421117	12/2022	Devita et al.	N/A	N/A
2023/0421119	12/2022	Komposch et al.	N/A	N/A

2024/0071962	12/2023	Noori et al.	N/A	N/A
2024/0106397	12/2023	Marbell et al.	N/A	N/A

## FOREIGN PATENT DOCUMENTS

Patent No.	Application Date	Country	CPC
1693891	12/2018	EP	N/A
3783663	12/2020	EP	N/A
H065634	12/1993	JP	N/A
H06267996	12/1993	JP	N/A
H1197616	12/1998	JP	N/A
2006066719	12/2005	JP	N/A
2006310726	12/2005	JP	N/A
2008193097	12/2007	JP	N/A
2010165789	12/2009	JP	N/A
2010183100	12/2009	JP	N/A
2011108813	12/2010	JP	N/A
2011171697	12/2010	JP	N/A
2011527113	12/2010	JP	N/A
2014099668	12/2013	JP	N/A
2015019002	12/2014	JP	N/A
2016207802	12/2015	JP	N/A
2017085013	12/2016	JP	N/A
2019096772	12/2018	JP	N/A
20140013618	12/2013	KR	N/A
20180019226	12/2017	KR	N/A
201810673	12/2017	TW	N/A
201813016	12/2017	TW	N/A
202013658	12/2019	TW	N/A
2004075336	12/2003	WO	N/A
2017029822	12/2016	WO	N/A
2019132941	12/2018	WO	N/A

## OTHER PUBLICATIONS

“Notification of Transmittal of the International Search Report and the Written Opinion of the International Searching Authority, or the Declaration for corresponding International Application No. PCT/US2021/021845, mailing date: Jul. 5, 2021, (14 pages)”. cited by applicant

“Notification of Transmittal of the International Search Report and the Written Opinion of the International Searching Authority, or the Declaration for corresponding International Application No. PCT/US2022/023916, mailing date: Jun. 30, 2021, (13 pages)”. cited by applicant

“Qin Zheng et al: “Electrical simulation of thin film inductors on silicon and glass substrates”, 2014 Joint IEEE International Symposium , IEEE, May 12, 2014, pp. 555-559”. cited by applicant

Notification of Transmittal of the International Search Report and the Written Opinion of the International Searching Authority, or the Declaration, in corresponding PCT Application No. PCT/US2021/024623 (Jul. 16, 2021). cited by applicant

Notification of Transmittal of the International Search Report and the Written Opinion of the International Searching Authority, or the Declaration, in corresponding PCT Application No. PCT/US2021/021848 (Jun. 18, 2021). cited by applicant

## Background/Summary

CLAIM OF PRIORITY (1) This application claims priority from U.S. Provisional Application No. 63/004,760 filed Apr. 3, 2020 with the United States Patent and Trademark Office, the disclosure of which is incorporated by reference herein.

### FIELD

(1) The present disclosure is directed to integrated circuit devices, and more particularly, to structures for integrated circuit device packaging.

### BACKGROUND

(2) RF power amplifiers are used in a variety of applications such as base stations for wireless communication systems, etc. The signals amplified by the RF power amplifiers often include signals that have a modulated carrier having frequencies in the megahertz (MHz) to gigahertz (GHz) range. The baseband signal that modulates the carrier is typically at a relatively lower frequency and, depending on the application, can be up to 300 MHz or higher. Many RF power amplifier designs utilize semiconductor switching devices as amplification devices. Examples of these switching devices include power transistor devices, such as MOSFETs (metal-oxide semiconductor field-effect transistors), DMOS (double-diffused metal-oxide semiconductor) transistors, HEMTs (high electron mobility transistors), MESFETs (metal-semiconductor field-effect transistors), LDMOS (laterally-diffused metal-oxide semiconductor) transistors, etc.

(3) RF amplifiers are typically formed as semiconductor integrated circuit chips. Most RF amplifiers are implemented in silicon or using wide bandgap semiconductor materials (i.e., having a band-gap greater than 1.40 eV), such as silicon carbide (“SiC”) and Group III nitride materials. As used herein, the term “Group III nitride” refers to those semiconducting compounds formed between nitrogen and the elements in Group III of the periodic table, usually aluminum (Al), gallium (Ga), and/or indium (In). The term also refers to ternary and quaternary compounds, such as AlGa<sub>N</sub> and AlInGa<sub>N</sub>. These compounds have empirical formulas in which one mole of nitrogen is combined with a total of one mole of the Group III elements.

(4) Silicon-based RF amplifiers are typically implemented using LDMOS transistors, and can exhibit high levels of linearity with relatively inexpensive fabrication. Group III nitride-based RF amplifiers are typically implemented using HEMTs, primarily in applications requiring high power and/or high frequency operation where LDMOS transistor amplifiers may have inherent performance limitations.

(5) RF transistor amplifiers may include one or more amplification stages, with each stage typically implemented as a transistor amplifier. In order to increase the output power and current handling capabilities, RF transistor amplifiers are typically implemented in a “unit cell” configuration in which a large number of individual “unit cell” transistors are arranged electrically in parallel. An RF transistor amplifier may be implemented as a single integrated circuit chip or “die,” or may include a plurality of dies. When multiple RF transistor amplifier die are used, they may be connected in series and/or in parallel.

(6) RF amplifiers often include matching circuits, such as impedance matching circuits, that are designed to improve the impedance match between the active transistor die (e.g., including MOSFETs, HEMTs, LDMOS, etc.) and transmission lines connected thereto for RF signals at the fundamental operating frequency, and harmonic termination circuits that are designed to at least partly terminate harmonic products that may be generated during device operation such as second

and third order harmonic products. The termination of the harmonic products also influences generation of intermodulation distortion products.

(7) The RF amplifier transistor die(s) as well as the impedance matching and harmonic termination circuits may be enclosed in a device package. A die or chip may refer to a small block of semiconducting material or other substrate on which electronic circuit elements are fabricated. Integrated circuit packaging may refer to encapsulating one or more dies in a supporting case or package that protects the dies from physical damage and/or corrosion, and supports the electrical contacts for connection to external circuits. The input and output impedance matching circuits in an integrated circuit device package typically include LC networks that provide at least a portion of an impedance matching circuit that is configured to match the impedance of the active transistor die to a fixed value. Electrical leads may extend from the package to electrically connect the RF amplifier to external circuit elements such as input and output RF transmission lines and bias voltage sources.

(8) Many functional blocks such as impedance matching circuits, harmonic filters, couplers, baluns, and power combiners/dividers can be realized by Integrated Passive Devices (IPDs). IPDs include passive electrical components and are generally fabricated using standard wafer fabrication technologies such as thin film and photolithography processing. IPDs can be designed as flip chip mountable or wire bondable components. The substrates for IPDs usually are thin film substrates like silicon, alumina, or glass, which may allow for ease in manufacturing and packaging with active transistor dies.

(9) Some conventional methods for assembling RF power devices may involve assembling the transistor die and some of the matching network components (e.g., pre-match capacitors, such as MOS capacitors) in a ceramic or over-molded package on a CPC (copper, copper-molybdenum, copper laminate structure) or copper flange. The transistor die, capacitors, and input/output leads may be interconnected with wires, such as gold and/or aluminum wires. Such an assembly process may be slow and sequential (e.g., one package bonded at a time), and assembly costs may be high (e.g., due to cost of gold wires and expensive wire-bond machines).

#### SUMMARY

(10) According to some embodiments of the present disclosure, an integrated circuit device package includes a substrate, a first die comprising active electronic components attached to the substrate, and at least one integrated interconnect structure on the first die opposite the substrate. The at least one integrated interconnect structure extends from the first die to an adjacent die attached to the substrate and/or toward at least one package lead and provides electrical connection therebetween.

(11) In some embodiments, the electrical connection may be free of a wire bond.

(12) In some embodiments, the first die may include a first bond pad, which is electrically connected to one or more of the active electronic components, on a surface of the first die opposite the substrate. The at least one integrated interconnect structure may include a contact pad that is on the first bond pad.

(13) In some embodiments, the at least one integrated interconnect structure may be a conductive wiring pattern on a redistribution layer.

(14) In some embodiments, the at least one integrated interconnect structure may include or provide at least a portion of an impedance matching network for a circuit defined by the active electronic components of the first die.

(15) In some embodiments, the at least one integrated interconnect structure may be a passive device including one or more passive electronic components.

(16) In some embodiments, the contact pad of the integrated interconnect structure may be a second bond pad, which is electrically connected to the one or more passive electronic components, on a surface of the passive device that is facing the surface of the first die. The second bond pad is connected to the first bond pad by a conductive bump therebetween.

(17) In some embodiments, the active electronic components of the first die may define a first radio frequency (RF) amplifier circuit. The adjacent die may be a second active die including active electronic components that define a second RF amplifier circuit. The first and second power amplifier circuits may be connected in a multi-stage amplifier arrangement by the passive device.

(18) In some embodiments, the passive device may be an integrated passive device (IPD) including at least one inductor.

(19) In some embodiments, the IPD may be free of active electronic components.

(20) In some embodiments, the IPD may include an insulating material between conductive elements thereof to define at least one capacitor integrated therein.

(21) In some embodiments, the adjacent die may be a capacitor die including one or more capacitors and at least one capacitor bond pad that is on a surface of the adjacent die opposite the substrate. The contact pad of the at least one integrated interconnect structure may be a first contact pad, and the at least one integrated interconnect structure may further include at least one second contact pad that is on the at least one capacitor bond pad.

(22) In some embodiments, the at least one package lead may be a gate lead and the first bond pad may be a gate pad. The adjacent die may be between the first die and the gate lead, and the impedance matching network may be an input impedance matching network for the circuit.

(23) In some embodiments, the at least one package lead may be a drain lead and the first bond pad is may be drain pad. The adjacent die may be between the first die and the drain lead, and the impedance matching network may be an output impedance matching network for the circuit.

(24) In some embodiments, the active electronic components may be power transistor devices. The first die may include a Group III-nitride and/or silicon carbide.

(25) According to some embodiments of the present disclosure, a radio frequency (RF) power amplifier device package includes a substrate, a first die including a plurality of transistor cells that is attached to the substrate at a source pad on a bottom surface thereof and a gate or drain pad at a top surface thereof opposite the substrate, package leads configured to conduct electrical signals between the gate or drain pad of the first die and an external device, and an integrated interconnect structure on the first die opposite the substrate. The integrated interconnect structure includes a first contact pad on the gate or drain pad, and at least one second contact pad on an adjacent die attached to the substrate and/or coupled to one of the package leads.

(26) In some embodiments, the integrated interconnect structure may provide electrical connection from the gate or drain pad of the first die to the adjacent die and/or to the one of the package leads. The electrical connection may be free of a wire bond.

(27) In some embodiments, the integrated interconnect structure may be a conductive wiring pattern on a redistribution layer, or a passive device including one or more passive electronic components.

(28) In some embodiments, the integrated interconnect structure may include or provide at least a portion of an impedance matching network for a circuit defined by the transistors of the first die.

(29) In some embodiments, the first contact pad of the integrated interconnect structure may be a bond pad, which is electrically connected to the one or more passive electronic components, on a surface of the passive device that is facing the top surface of the first die. The bond pad may be connected to the gate or drain pad by a conductive bump therebetween.

(30) In some embodiments, the adjacent die may include at least one bond pad on a surface thereof opposite the substrate. The at least one second contact pad of the integrated interconnect structure may be on the at least one bond pad. The adjacent die may be a capacitor die including one or more capacitors, or may be a second die including a plurality of transistor cells that define a stage of an RF amplifier circuit.

(31) Other devices, apparatus, and/or methods according to some embodiments will become apparent to one with skill in the art upon review of the following drawings and detailed description. It is intended that all such additional embodiments, in addition to any and all combinations of the

above embodiments, be included within this description, be within the scope of the invention, and be protected by the accompanying claims.

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## Description

### BRIEF DESCRIPTION OF THE DRAWINGS

- (1) FIGS. 1A, 1B, and 1C are cross-sectional views illustrating examples of integrated circuit device packages including stacked topology structures in accordance with some embodiments of the present disclosure.
- (2) FIG. 1D is an equivalent circuit diagram of the embodiments of FIGS. 1A, 1B, and 1C.
- (3) FIGS. 2A and 2B are cross-sectional views illustrating examples of integrated circuit device packages including stacked topology structures in accordance with some embodiments of the present disclosure.
- (4) FIG. 2C is an equivalent circuit diagram of the embodiments of FIGS. 2A and 2B.
- (5) FIG. 3A is a cross-sectional view illustrating an example of an integrated circuit device package including stacked topology structures in accordance with some embodiments of the present disclosure.
- (6) FIG. 3B is an equivalent circuit diagram of the embodiment of FIG. 3A.
- (7) FIG. 4A is a cross-sectional view illustrating an example of an integrated circuit device package including stacked topology structures in accordance with some embodiments of the present disclosure.
- (8) FIG. 4B is an equivalent circuit diagram of the embodiment of FIG. 4A.
- (9) FIG. 5A is a cross-sectional view illustrating an example of an integrated circuit device package including stacked topology structures in accordance with some embodiments of the present disclosure.
- (10) FIG. 5B an equivalent circuit diagram of the embodiment of FIG. 5A.
- (11) FIG. 5C is a bottom plan view illustrating a package footprint of the embodiment of FIG. 5A in accordance with some embodiments of the present disclosure.
- (12) FIG. 5D is a top plan view illustrating the package footprint of the embodiment of FIG. 5C in accordance with some embodiments of the present disclosure.
- (13) FIGS. 6A and 6B are cross-sectional views illustrating examples of integrated circuit device packages including stacked topology structures in accordance with some embodiments of the present disclosure.
- (14) FIG. 6C is an equivalent circuit diagram of the embodiments of FIGS. 6A and 6B.
- (15) FIG. 7A is a cross-sectional view illustrating an example of an integrated circuit device package including stacked topology structures in accordance with some embodiments of the present disclosure.
- (16) FIG. 7B is an equivalent circuit diagram of the embodiments of FIG. 7A.
- (17) FIGS. 8A and 9A are cross-sectional views illustrating examples of sub-components of integrated circuit device packages including stacked topology structures in accordance with some embodiments of the present disclosure.
- (18) FIGS. 8B and 9B are equivalent circuit diagrams of the embodiments of FIGS. 8A and 9A, respectively.
- (19) FIGS. 10A and 10B are plan and perspective views, respectively, illustrating examples of high-Q IPDs in accordance with some embodiments of the present disclosure.
- (20) FIGS. 11 and 12 are cross-sectional views illustrating examples of thermally enhanced integrated circuit device packages including stacked topology structures in accordance with further embodiments of the present disclosure.
- (21) FIG. 13 is a cross-sectional view that is taken through a portion of the top side metallization



structure of FIG. 1A.

## DETAILED DESCRIPTION

(22) Some embodiments of the present disclosure may arise from difficulties in assembling and optimizing parameters of the various components included in an integrated circuit device package. For example, performance of some passive electronic components (e.g., inductors or capacitors) included in a die or IPD (generally referred to herein as a passive device or passive RF device), may be affected based on proximity to a ground plane. In particular, the quality factor  $Q$  of inductor coils may be reduced as a distance between the windings of the inductor coils and a ground-connected flange (or other grounded structure) is reduced. However, as dies are typically planar structures with only one surface providing conductive contact elements (also referred to herein as contact pads, bond pads, or pads) for electrical connections (typically by bondwires) to external dies or devices, increasing the distance between the passive components and the ground plane may increase the length of connections with one or more active electronic components (e.g., transistors, such as power transistor devices including transistor cells) included in an active transistor die (also referred to herein as a transistor die or active die). The increased connection lengths may reduce or negate the effectiveness of the impedance matching networks provided by the passive components, particularly at higher frequencies. Output pre-matching networks using a shunt inductor (“shunt-L”) topology may be challenging (e.g., for GaN die products) because the long shunt-L bondwires may introduce more inductance than needed, degrading the quality of the impedance match (e.g., due in part to lower drain to source capacitance ( $C_{sub.ds}$ )/watt in GaN), at about 50-70 fF/watt, which may likewise lead to higher losses and reduced performance. Coupling between input (e.g., gate) and output (e.g., drain) bond-wires may also lead to gain loss and instability.

(23) In contrast to some conventional RF power devices that may use wire-bond loops to implement input and output pre-matching, embodiments of the present disclosure provide packaged RF power products for high power applications, in which connections between components (e.g., between circuit-level components, such as between the bond pads of one or more active transistor dies, and/or between the bond pads of active transistor dies and the gate and/or drain leads of the package) are implemented by one or more structures including conductive components on a layer or substrate, such as semiconductor chips or dies (e.g., one or more passive devices) without the use of wirebonds, generally referred to herein as integrated interconnect structures.

(24) An integrated interconnect structure or device (or ‘integrated interconnect’) may generally refer to a structure that includes integrated circuitry such as resistors (including transmission lines), vias, inductors, and/or capacitors on a layer or substrate, for example, a dielectric base structure with integrated traces, vias and/or circuitry that can be used instead of bond wires to reduce and/or avoid related parasitic induction and manufacturing issues. Integrated interconnects may be implemented in some embodiments described herein as passive devices (including IPDs with thin film substrates such as silicon, alumina, or glass) and/or conductive wiring structures (including conductive wires on a redistribution layer (RDL) laminate structure or other substrate). As noted above, IPDs include inductors and/or other passive electrical components, and may be fabricated using standard semiconductor processing techniques such as thin film and/or photolithography processing. IPDs can be flip chip mountable or wire bondable components, and may include thin film substrates such as silicon, alumina, or glass. An RDL structure refers to a substrate or laminate that has conductive layer patterns and/or conductive vias. RDL structures may be fabricated using semiconductor processing techniques by depositing conductive and insulating layers and/or patterns on a base material and by forming vias and copper routing patterns within the structure for transmitting signals through the RDL structure.

(25) Integrated interconnects may be used as described herein to provide connections to inputs, outputs, and/or between stages of transistor dies, as well as to provide circuits that may be useful and/or necessary for operation of the transistor die(s). For example, the integrated interconnects may provide an impedance that is configured to reduce an impedance mismatch between active

transistors dies, and/or between an external device connected to the package leads. In particular examples, input and/or output pre-matching network circuits for an active transistor die can be implemented by integrated interconnects, such as IPDs, resulting in minimal or no wire-bonding. In some embodiments, flip-chip IPDs including respective contacts that face the respective contacts of the one or more transistor dies may be used to interconnect multiple transistor dies, for example, in multi-stage amplifier implementations. That is, in some embodiments, the integrated interconnects may provide both an interconnection function and an impedance matching/harmonic termination function, such that the use of wirebonds in the package can be reduced or eliminated. IPDs as described herein may be free of active components in some embodiments.

(26) In some embodiments, the IPDs that provide the impedance matching networks for the active die (also referred to herein as pre-match IPDs) are placed or stacked directly on top of the gate and/or drain pads of the transistor die and/or capacitor chips, thus reducing or minimizing interconnect-related losses. The elevated height or increased distance (as provided by the stacked arrangement, for example, on top of a 100  $\mu\text{m}$  thick active transistor die) between the passive components and an attachment surface, such as the ground-connected flange of a device package die pad or flange of the package, can reduce capacitive coupling to ground, thus reducing or minimizing negative effects on (and in some cases increasing) the quality factor  $Q$  (minimizing losses) of the passive components, and leading to better RF performance. Also, the thin, low-profile conductive traces in the integrated interconnects (e.g., the pre-match IPDs) may have lower coupling to output wires or traces.

(27) Additional passive components (e.g., for particular applications) can be included in the passive device and/or on the attachment surface of the package directly beneath the passive device. For example, in some embodiments, capacitors for pre-matching and/or harmonic termination (e.g., MOS capacitors) can be placed between the input pre-match IPD and the attachment surface. Similarly, high density output capacitors can be placed between the output pre-match IPD and the attachment surface for improved video bandwidth (VBW), providing a larger area for use in housing the high-density VBW capacitors. In some embodiments, the passive device may include capacitors integrated therein, such as MIM (metal-insulator-metal) capacitors.

(28) Embodiments of the present disclosure can thus use stacked chip topologies to greatly reduce problems of coupling between gate and drain bond-wires, which can lead to gain loss and instability. In some embodiments, gate and/or drain bond-wires can be eliminated or reduced, and the low-profile conductive traces in the integrated interconnects (e.g., the input and/or output IPDs) may provide little coupling therebetween and/or lower coupling to output wires or traces. Also, by implementing the shunt-L and series connecting inductance in a high-Q flip-chip IPD, the required inductance can be achieved in a smaller area, and with manageable losses.

(29) Embodiments of the present disclosure can be used in RF power products for 5G and base-station applications, as well as in radar and/or monolithic microwave integrated circuit (“MMIC”) type applications. For example, Group III nitride-based RF amplifiers may be implemented as MMIC devices in which one or more transistor dies are implemented together with their associated impedance matching and harmonic termination circuits in a single, integrated circuit die.

(30) FIG. 1A is a cross-sectional view illustrating an example of an integrated circuit device package including stacked topology structures in accordance with some embodiments of the present disclosure. As shown in FIG. 1A, some embodiments of the present disclosure provide an RF power device package **100a**, which includes an active die **105** and integrated interconnects (illustrated as passive devices **110i**, **110o**; collectively **110**) assembled on a package substrate **101a**. In the example of FIG. 1A, the substrate **101a** is a redistribution layer (RDL) laminate structure. The RDL **101a** may include conductive layers fabricated using semiconductor processing techniques. However, it will be understood that the substrate **101a** is not so limited: for example, the substrate **101a** may be a printed circuit board (e.g., a multi-layer printed circuit board with metal traces), a ceramic substrate that includes conductive vias and/or conductive pads or any other

suitable mounting surface for the active die **105**. The bottom surface or bottom side of the RDL **101a** includes package leads (in particular, gate **102g**, drain **102d**, and source **102s** leads, collectively package leads **102**) that conduct electrical signals between components on an attachment surface **101s** of the RDL **101a** and an external device (not shown), such as an external circuit board. The attachment surface **101s** may include one or more conductive die pads, which in some embodiments may provide an electrical ground for the components of the package **100**. The RDL **101a** includes vias and multi-layer copper routing for transmitting signals from the leads **102** to passive electronic components (such as capacitor chips including one or more MOS capacitors **104** or high density capacitors **106**) and active electronic components (such as transistors) of the active transistor die **105**. For example, the active die **105** may include power transistor devices, e.g., defining an RF power amplifier. In some embodiments, the active die **105** may include discrete multi-stage, MMIC, and/or multi-path (e.g., Doherty) transistor devices.

(31) The active transistor dies described herein may be implemented in silicon or using wide bandgap semiconductor materials, such as silicon carbide (“SiC”) and Group III nitride materials. In particular embodiments, the active dies may be Group III nitride-based, such as gallium nitride (GaN), and/or silicon carbide (SiC)-based, including unit cell transistors that are connected in parallel in an upper portion of a semiconductor layer structure. The term “semiconductor layer structure” may refer to a structure that includes one or more semiconductor layers, such as semiconductor substrates and/or semiconductor epitaxial layers. In the illustrated embodiments, the active transistor die includes a gate pad and/or drain pad on an upper surface, and a source pad on a lower surface of the semiconductor layer structure that is adjacent the attachment surface. It will be understood, however, that this die configuration is illustrated herein by way of example only, and that embodiments and/or topologies described herein can be used with die configurations other than those specifically illustrated.

(32) As RF amplifiers are often used in high power and/or high frequency applications, high levels of heat may be generated within the transistor die(s) during operation. If the transistor die(s) become too hot, the performance (e.g., output power, efficiency, linearity, gain, etc.) of the RF amplifier may deteriorate and/or the transistor die(s) may be damaged. As such, RF amplifiers are typically mounted in packages that may be optimized or otherwise configured for heat removal. In the example of FIG. 1A, the source lead **102s** includes or is attached to a conductive structure **103** (illustrated as an embedded conductive slug or via) that provides thermal conductivity (e.g., a heat sink). In particular, a section of the RDL **101a** underneath the transistor die **105** may be filled (e.g., greater than about 85% filled, fully filled, or almost fully filled) with a high-density conductive array **103** of copper vias for transmitting heat away from the transistors of the transistor die **105**. The conductive structure **103** may also be filled with an embedded copper slug or coin for example, in an embedded packaging process. The transistor die **105** and capacitor chips **104**, **106** are attached to the attachment surface **101s** of the RDL **101a** with die-attach materials **107** and techniques, such as eutectic materials, precoat (e.g., AuSn precoat), pre-forms, sintering (e.g., Ag-sintering), etc.

(33) Still referring to FIG. 1A, one or more connections between the active transistor die **105** (in particular, between contacts or bond pads **105p** on a top side or surface of the transistor die **105**) and the package leads **102** are implemented by respective integrated interconnects, in this example passive devices implemented by IPDs **110i** and **110o**, without wire bonds therebetween. The connections provided by the passive devices **110** are opposite to (rather than in) the attachment surface **101s** or substrate **101a**, to which the bottom side or surface of the active die **105** is attached. More particularly, the bond pads **105p** on a surface of the transistor die **105** opposite the substrate **101** are connected to bond pads **110p** on a surface of the IPDs **110** facing the transistor die **105**, and the bond pads **110p** of the IPDs are connected to the package leads **102**. As noted above, the passive device(s) **110** may include passive electronic components such as resistors/transmission lines, inductors, and/or capacitors on a semiconductor or other substrate.

(34) In FIG. 1A, the components of the passive devices **110** are configured to provide input **110i** and output **110o** impedance matching networks for a circuit (e.g., an RF amplifier circuit) defined by transistors of the active die **105**, and are illustrated as high-Q IPDs, but passive devices as described herein are not limited thereto. The input impedance matching circuits may match the impedance of the fundamental component of RF signals input to the RF power device package **100a** to the impedance at the input of the active die **105**, the output impedance matching circuits may match the impedance of the fundamental component of RF signals that are output from the RF power device package **100a** to the impedance of the circuitry connected to the output of the active die **105**, and input and/or output harmonic termination circuits are configured to short to ground harmonics of the fundamental RF signal that may be present at the input and/or output of the active die **105**.

(35) In the example of FIG. 1A, the high-Q IPDs **110** for the input and output pre-matching networks are flip-chip devices including respective bond pads **110p** on a surface of the IPDs **110**. The IPDs **110** are thus 'flip-chipped' on top of the transistor die **105** and capacitor chips **104**, **106**, such that the bond pads **110p** on surfaces of the IPDs **110** are aligned with bond pads **105p** and **104p**, **106p** on surfaces of the transistor die **105** and the capacitor chips **104**, **106**, respectively, that are facing the surface of the IPDs **110**. The IPDs **110** may include conductive bumps **111** (e.g., conductive epoxy patterns or solder bumps, in some embodiments pre-attached to the IPDs **110**) for connecting the bond pads **110p** to the bond pads **105p** and **104p**, **106p**. The top surfaces of the capacitor chips **104**, **106** and transistor die **105** can be aligned to the same height by grinding the wafers (for the die or capacitor chips), and/or or by using pre-forms **107** of different thicknesses to align the heights of the elements **104**, **105**, and **106**. As such, the package **100a** includes a stacked structure with elements **104**, **105**, and **106** attached to the attachment surface **101s** (which may provide electrical connection to ground) between the substrate **101a** and the elements **110**. The elements **110** provide electrical connections between the elements **104**, **105**, and **106** and the leads **102** opposite to the substrate **101a**, and without respective bond wires extending between the elements **104**, **105**, and **106** and the leads **102**.

(36) A copper shim **112** attached to the RDL **101a** can be used for routing the signal from the IPDs **110** to the RDL **101a** and to the gate and drain leads **102g** and **102d** of the package **100a**. In some embodiments, additional IPDs including vias (e.g., through silicon vias (TSVs)) can be used in place of the copper shim **112** to connect the IPDs **110** to the gate and drain leads **102g** and **102d**.

(37) A packaging material (illustrated as a plastic over mold (OMP) **113**) encapsulates or otherwise provides protection for the dies **105**, **110** while providing access to the leads **102** for connection to circuits or devices that are external to the package **100a**, generally referred to herein as external devices. The over-mold **113** may substantially surround the dies **105**, **110**, and may be formed of a plastic or a plastic polymer compound, thereby providing protection from the outside environment. Advantages of the over mold type package include reduced overall height or thickness of the package, and design flexibility for the arrangement of and/or spacing between the leads **102**. In some embodiments, over mold-type packages as described herein may have a height or OMP thickness of about 400 micrometers ( $\mu\text{m}$ ) to about 700  $\mu\text{m}$ . In other embodiments, the dies **105**, **110** may be included in an open cavity package (e.g., a thermally enhanced package (TEPAC or T3PAC)), including ceramic materials, that defines a cavity surrounding the dies **105**, **110** and may have a height or thickness of about 1400 micrometers ( $\mu\text{m}$ ) to about 1700  $\mu\text{m}$ .

(38) FIG. 1B is a cross-sectional view illustrating another example of an integrated circuit device package including stacked topology structures in accordance with some embodiments of the present disclosure. As shown in FIG. 1B, an RF power device package **100b** includes active and passive devices **105**, **110** assembled on a substrate **101b**. The package **100b** includes components and connections as in the embodiment shown in FIG. 1A, but the substrate **101b** is a conductive structure **103** (e.g., a copper slug) that provides the attachment surface **101s**, the source lead **102s**, and thermal conductivity (e.g., a heat sink) for transmitting heat away from the transistors of the

transistor die **105**. Also, in comparison to FIG. 1A, the bond pads **110p** of the passive devices **110** are connected to the package leads **102** by an integrated interconnect (illustrated as conductive wiring structures **114**, e.g., including a copper routing layer in a RDL), instead of the copper shims **112** (or IPD with TSVs). Alternatively, the bond pads **110p** of the passive devices **110** can be directly connected to the package leads **102** (e.g., by respective solder bumps **111**) in some embodiments, without the conductive wiring structures **114** therebetween. The embodiment of FIG. 1B may be described as lead-frame based, in comparison to the laminate based embodiment of FIG. 1A.

(39) FIG. 1C is a cross-sectional view illustrating another example of an integrated circuit device package including stacked topology structures in accordance with some embodiments of the present disclosure. As shown in FIG. 1C, an RF power device package **100c** is similar to the embodiment of FIG. 1A, but instead of the copper shims **112** (or IPD with TSVs), the package **100c** includes second RDL layers **101c** attached on top of the first RDL layer **101a**, opposite the gate lead **102g** and/or opposite the drain lead **102d**. The height or thickness of the second RDL layer **101c** is selected or configured to provide a contact surface that is aligned or coplanar with the bump pads **105p**, **104p** of the transistor die **105** and MOS capacitor chip **104** at the input side, and likewise, aligned or coplanar with the bump pads **105p**, **106p** of the transistor die **105** and VBW capacitor chip **106** at the output side. As such, the input **110i** and output **110o** flip-chip IPDs can be placed on substantially coplanar surfaces provided by the second RDL layer **101b** to interconnect the gate and drain pads **105p** of the transistor die **105** with the gate lead **102g** and drain lead **102d** (and/or with the MOS capacitors **104** and VBW capacitors **106**). Additional second RDL layers **101c** and/or other intermediate substrates, while not illustrated, may also be provided between the attachment surface **101s** and the passive device(s) **110** to provide the desired clearance or alignment between contact pads of components of different heights or thicknesses.

(40) FIG. 1D is an equivalent circuit diagram of the embodiments in FIGS. 1A, 1B, and 1C. The input pre-matching network is implemented by the high-Q IPD **110i** and the input capacitors **104** to provide an L-C matching circuit (e.g., a low-pass L-C) at the fundamental frequency  $f_0$ , as well as a shunt-L inductance  $L_s$  matching circuit (e.g., a high-pass  $L_s$ ) for optimum termination of the harmonic frequencies (e.g.,  $2f_0$ ). The output pre-matching network is implemented by the output capacitors **106** and the high-Q IPD **110** to provide a shunt-L inductance  $L_s$  matching circuit (e.g., a high-pass  $L_s$ ) for pre-matching the fundamental frequency  $f_0$ . The series transmission lines **110r** in each of the input **110i** and output **110o** IPDs can be selected to provide appropriate impedance transformation from the transistor die **105** to the gate **102g** or drain **102d** leads. The series transmission lines (e.g., as provided by conductive structures **110r**) can be treated as an extension of the board transmission line matching network, and electrical widths can be selected or configured to achieve the desired characteristic impedance for the impedance matching.

(41) FIGS. 2A and 2B are cross-sectional views illustrating examples of integrated circuit device packages including stacked topology structures in accordance with some embodiments of the present disclosure. As shown in FIGS. 2A and 2B, RF power device package **200a** and **200b** each includes an active die **105** and an integrated interconnect (illustrated as an IPD or other passive device **110i**) assembled on a package substrate **201**. The packages **200a** and **200b** include components and connections as in the embodiment shown in FIG. 1B, with the substrate **201** implemented as a conductive structure **103** (e.g., a copper slug) that provides the attachment surface **201s**, the source lead **102s**, and thermal conductivity (e.g., a heat sink) for transmitting heat away from the transistors of the transistor die **105**. In the embodiments of FIGS. 2A and 2B, the passive device **110** is used only at the input side of the package **200a**, **200b**. For example, for implementations with smaller die periphery (e.g., less than about 16 mm total gate width) and/or lower frequency operation (e.g., less than about 2.4 GHz), the output impedance of the transistor die **105** may be sufficiently high to be matched to 50 ohms with an RF circuit board, such that an in-package output pre-matching network may not be needed. As only an input pre-matching

network may be required in some implementations, the input of the transistor die **105** is electrically connected to the gate lead **102g** by the IPD **110i** and the MOS capacitors **104** defining the pre-matching network.

(42) More particularly, the bond pads **105p** and **104p** on top surfaces of the transistor die **105** and the MOS capacitor chips **104** are connected to bond pads **110p** on a facing surface of the IPD **110i** by respective solder bumps **111**, without wire bonds therebetween. The bond pads **110p** of the IPD **110i** are connected to the gate lead **102g** by conductive wiring structures **114**, for example a copper routing layer in a RDL. Alternatively, the bond pads **110p** of the passive device **110i** can be directly connected to the gate lead **102g**, without the conductive wiring structures **114** therebetween. The output of the transistor die **105** is connected directly to the drain lead **102d** by conductive wiring structures (illustrated as a copper routing layer in a RDL **214** in FIG. 2A or as a wire-bond **14** in FIG. 2B).

(43) FIG. 2C is an equivalent circuit diagram representing the embodiments of FIGS. 2A and 2B. Similar to the input side in the embodiments of FIGS. 1A and 1B, the input pre-matching network is implemented by the high-Q IPD **110i** and the input capacitors **104** to provide an L-C matching circuit (e.g., a low-pass L-C) at the fundamental frequency  $f_0$ , as well as a shunt-L inductance  $L_s$  matching circuit (e.g., a high-pass  $L_s$ ) for optimum termination of one or more harmonic frequencies (e.g.,  $2f_0$ ). The series transmission line **110r** in the input **110i** IPD can be selected to provide appropriate impedance transformation from the transistor die **105** to the gate lead **102g**. Electrical width of the transmission line **110r** may also be configured to achieve the desired characteristic impedance for the impedance matching.

(44) FIG. 3A is a cross-sectional view illustrating an example of an integrated circuit device package including stacked topology structures in accordance with some embodiments of the present disclosure. As shown in FIG. 3A, RF power device package **300** includes an active die **105** and an integrated interconnect (illustrated as an IPD or other passive device **110o**) assembled on a package substrate **301**. As in the embodiment of FIG. 1B, the substrate **301** is a conductive structure **103** (e.g., a copper slug) that provides the attachment surface **301s**, the source lead **102s**, and thermal conductivity (e.g., a heat sink) for transmitting heat away from the transistors of the transistor die **105**. In the embodiments of FIG. 3A, the passive device **110o** that provides electrical connections to the active die **105** and the capacitor chip **106** is provided only at the output side of the package **300**. More particularly, the bond pads **105p** and **106p** of the transistor die **105** and the high density capacitor chip **106** are connected to bond pads **110p** of the IPD **110o** by respective conductive bumps **111**, without wire bonds therebetween. The bond pads **110p** of the IPD **110o** are connected to the drain lead **102d** by conductive wiring structures **114**, for example a copper routing layer in a RDL. Alternatively, the bond pads **110p** of the passive device **110o** can be directly connected to the drain lead **102d**, without the conductive wiring structures **114** therebetween.

(45) Still referring to FIG. 3A, the connections between the gate lead **102g**, the capacitor chip **104**, and the input of the transistor die **105** are implemented by integrated interconnects in the form of conductive wiring structures **314**, illustrated as a RDL including a copper (or other conductive) routing layer and a contact pad, illustrated by way of example as a conductive via or post **314v**. More particularly, in the example of FIG. 3A, the inductance for the input pre-matching network and harmonic termination is implemented directly in the copper trace and vias of the RDL **314**, and the input IPD **110i** is omitted. The inductance for the impedance matching can be achieved in the conductive wiring structure **314**, for example, using narrow strips of copper routing or coil tracing, and can be connected to the bond pads **105p** and **104p** of the transistor die **105** and input capacitor chip **104** using conductive vias **314v**. For example, narrow copper traces (e.g., about 10 microns in width) and vias can be deposited using modern embedded packaging assembly techniques to collectively provide the RDL **314** with the required or desired inductance in some embodiments. However, the tolerance of the trace width and/or spacing of the traces and/or vias of the RDL **314** may be less controllable as compared to an IPD **110**.

(46) FIG. 3B is an equivalent circuit diagram representing the embodiment of FIG. 3A. Similar to the output side in the embodiments of FIGS. 1A and 1B, the output pre-matching network is implemented by the output capacitors **106** and the high-Q IPD **110o** to provide a shunt-L inductance  $L_s$  matching circuit (e.g., a high-pass  $L_s$ ) for pre-matching the fundamental frequency  $f_0$ . The series transmission line **110r** in the output IPD **110o** can be selected to provide appropriate impedance transformation from the transistor die **105** to the drain **102d** lead. The input pre-matching network is implemented by the conductive wiring structure **314** and the input capacitors **104** to provide an L-C matching circuit (e.g., a low-pass L-C) at the fundamental frequency  $f_0$ , as well as a shunt-L inductance  $L_s$  matching circuit (e.g., a high-pass  $L_s$ ) for optimum termination of one or more harmonic frequencies (e.g.,  $2f_0$ ). The series transmission line **310r** implemented in the conductive wiring structure **314** can likewise be selected to provide appropriate impedance transformation from the transistor die **105** to the gate lead **102g**.

(47) FIG. 4A is a cross-sectional view illustrating an example of an integrated circuit device package including stacked topology structures in accordance with some embodiments of the present disclosure. As shown in FIG. 4A, RF power device package **400** includes an active die **105** and an integrated interconnect (illustrated as an IPD or other passive device **110oc**) assembled on a substrate **301**. As in the embodiment of FIG. 3A, the substrate **301** is a conductive structure **103** (e.g., a copper slug) that provides the attachment surface **301s**, the source lead **102s**, and thermal conductivity. The connections between the gate lead **102g**, the capacitor chip **104**, and the input of the transistor die **105** are implemented by conductive wiring structures **314**, with the inductance for the input pre-matching network and harmonic termination implemented directly in the conductive traces and vias of the wiring structure **314**. The passive device **110oc** that provides electrical connections to the active die **105** is provided only at the output side of the package **500**.

(48) In FIG. 4A, the output capacitor chip **106** (e.g., high-density capacitors, which may be used for video bandwidth) are not located beneath the output IPD **110oc**; rather, the output capacitance is integrated into the flip-chip output IPD **110oc**, e.g., as metal-insulator-metal (MIM) capacitors  $C$ . The MIM capacitors  $C$  may be formed by providing an insulating material between one of the conductive elements of the IPD **110oc** and one or more of the bond pads **110p** in some embodiments. At least one conductive via or post **410v** is used to connect one end of the integrated capacitor to the package ground, e.g., as provided by the conductive structure **103**. In some embodiments, the conductive via(s) **410v** may be implemented by copper via(s) in a RDL. The integration of the capacitance into the passive device **110oc** shown in FIG. 4A can be used in any of the embodiments described herein, and can create a higher Q (lower loss) output pre-match, as the flip-chip IPD process is typically done with high-resistive silicon substrate, which has less losses than a MOS capacitor that may be placed beneath the flip-chip IPD. High-density video bandwidth (VBW) capacitors can still be connected to the output-pre-match IPD **110oc** from a different location in the package **400**.

(49) FIG. 4B is an equivalent circuit diagram representing the embodiment of FIG. 4A. The output pre-matching network is implemented by a high-Q IPD **110oc** and an integrated output capacitance (e.g., implemented by MIM capacitor  $C$ ) to provide a shunt-L inductance  $L_s$  matching circuit (e.g., a high-pass  $L_s$ ) for pre-matching the fundamental frequency  $f_0$ . The integrated output capacitance  $C$  provided by the IPD **110oc** is connected to the package ground by the conductive via **410v** (which may itself provide some resistance and inductance). The series transmission line **110r** in the output IPD **110oc** can be selected to provide appropriate impedance transformation from the transistor die **105** to the drain **102d** lead. The input pre-matching network is implemented by the conductive wiring structure **314** and the input capacitors **104** to provide an L-C matching circuit (e.g., a low-pass L-C) at the fundamental frequency  $f_0$ , as well as a shunt-L inductance  $L_s$  matching circuit (e.g., a high-pass  $L_s$ ), and the series transmission line **310r** can likewise be selected to provide appropriate impedance transformation from the transistor die **105** to the gate lead **102g**.

(50) FIG. 5A is a cross-sectional view illustrating an example of an integrated circuit device package including stacked topology structures in accordance with some embodiments of the present disclosure. As shown in FIG. 5A, RF power device package **500** includes an active die **105** and an integrated interconnect (illustrated as an IPD or other passive device **110oc**) assembled on a package substrate **501**, which is implemented as a conductive structure **103** (e.g., a copper slug) that provides the attachment surface **501s**, the source lead **102s**, and thermal conductivity as in some other embodiments described herein. Likewise, the connections between the gate lead **102g**, the capacitor chip **104**, and the input of the transistor die **105** are implemented by conductive wiring structures **314**, with the inductance for the input pre-matching network and harmonic termination implemented directly in the conductive traces and vias of the wiring structure **314**. Also, similar to the embodiment of FIG. 4A, the passive device that provides electrical connections to the active die **105** is provided only at the output side of the package **500**, and is implemented by a flip-chip IPD **110oc** that includes the output capacitance integrated therein, with at least one conductive via **410v** (e.g., copper via in RDL) connecting the integrated capacitor to the package ground.

(51) In the embodiment of FIG. 5A, the series connection from the drain pad **105p** of the transistor die **105** to the package drain lead **102d** is shortened (as compared to the embodiment of FIG. 4A), in this example by positioning the package drain lead **102d** adjacent to the source/thermal lead **102s**, and in between the source/thermal lead **102s** and the ground node G for the output capacitor. The embodiment of FIG. 5A may thus be advantageous in that inductance between the drain pad **105p** of the transistor die **105** and the package drain lead **102d** can be reduced to a very low value, which may be helpful and/or critical to performance in higher frequency operation, e.g. above 3 GHz operating frequency.

(52) FIG. 5B an equivalent circuit diagram representing the embodiment of FIG. 5A, and may be similar to the equivalent circuit of FIG. 4B with respect to the input pre-matching network provided by the conductive wiring structure **314** and the input capacitors **104**. The output pre-matching network is implemented by the flip-chip IPD **110oc**, which provides a shunt-L inductance  $L_s$  matching circuit (e.g., a high-pass  $L_s$ ) with the output capacitance  $C$  integrated therein and connected to the ground lead G by conductive via **410v**.

(53) As shown in FIGS. 5A and 5B, since the drain lead **102d** exits the package **500** between the conductive structure **103** and output ground lead G, embodiments described herein provide a package footprint **500f** and PCB circuit designs **515i**, **515o** to support this topology. FIG. 5C is a plan view illustrating the package footprint **500f** for the embodiment of FIG. 5A. As shown in FIG. 5C, the ground connection to the output capacitance  $C$  integrated in the output IPD **110oc** is implemented by multiple (shown as three) smaller ground leads G opposite the source/thermal lead **102s**, with the drain lead **102d** therebetween. The output ground lead(s) G can be aligned with corresponding grounded vias **515v** in and to external circuit board **515**, such as an RF circuit board as shown in FIG. 5D.

(54) In particular, FIG. 5D is a top plan view with a transparent package **500** that illustrates the underside of the package footprint **500f** of FIG. 5C, and further illustrates the connections to an input matching circuit board **515i** and an output matching circuit board **515o** of the external circuit board **515**. The input and output matching circuit boards **515i**, **515o** may include additional active and/or passive electrical components in some embodiments. The ground leads G may be large enough (e.g., in terms of surface area relative to the footprint **500f**) to be manufactured, but small enough to not substantially degrade the performance of the output matching circuit board **515o**.

(55) FIGS. 6A and 6B are cross-sectional views illustrating examples of integrated circuit device packages including stacked topology structures in accordance with some embodiments of the present disclosure. As shown in FIGS. 6A and 6B, RF power device packages **600a** and **600b** include active dies **605i**, **605o** and an integrated interconnect (illustrated as an IPD or other passive device **610**) assembled on a substrate **101**. As in FIG. 1B, the substrate **101** is implemented as a



conductive structure **103** (e.g., a copper slug) that provides the attachment surface **101s**, the source lead **102s**, and thermal conductivity (e.g., a heat sink) for transmitting heat away from the transistors of the transistor dies **605i**, **605o**, and the connections provided by the passive devices **610** are opposite to (rather than in) the attachment surface **101s** or substrate **101**.

(56) In the embodiments of FIGS. **6A** and **6B**, the active dies **605i**, **605o** define a multi-stage packaged RF power amplifier device (shown as two stages by way of example). For example, the active die **605i** may be a smaller transistor die to implement the driver stage, and the active die **605o** may be larger transistor die **605o** (e.g., about 7 to 10 times larger in periphery than the driver stage transistor die **605i**) to implement the output or final stage of the amplifier. The transistor dies **605i**, **605o** are attached to the attachment surface **101s** of the substrate **101**/conductive structure **103** that provides the source/thermal lead **102s**, with inter-stage capacitor chip **604** on the attachment surface **101s** between the dies **605i**, **605o**. An inter-stage passive device **610** is attached to and provides electrical connections between the two transistor dies **605i**, **605o**.

(57) In particular, as shown in FIGS. **6A** and **6B**, an IPD **610** is flip-chip mounted on top of the transistor dies **605i**, **605o** and inter-stage matching capacitor chip **604**, such that the bond pads **610p** of the IPD **610** are aligned with bond pads **605p** and **604p** of the transistor dies **605i**, **605o** and the capacitor chip **604**. In particular, the bond pads **610p** of the IPD **610** may contact one or more bond pads **605p** of the driver stage transistor die **605i** that provides a driver drain lead **605d**, and one or more bond pads **605p** of the output stage transistor die **605o** that provides an output gate lead **605g**. The IPD **610** may include conductive bumps **111** (e.g., conductive epoxy patterns or solder bumps, in some embodiments pre-attached to the IPD **610**) for connecting the bond pads **610p** to the bond pads **605p** and **604p**, without wire bonds therebetween. The top surfaces of the capacitor chip **604** and transistor dies **605i**, **605o** can be aligned to the same height by grinding the wafers (for the die or capacitor chip), and/or or by using pre-forms **107** of different thicknesses to align the heights of the elements **604**, **605i**, **605o** for connection using the IPD **610**.

(58) In the multi-stage amplifier of FIGS. **6A** and **6B**, the IPD **610** includes passive components that define an inter-stage matching network that is configured to provide impedance matching between the output of the driver stage transistor die **605i** and the input of the output stage transistor die **605o**, that is, to match the load of the driver die **605i** to the input of the final die **605o**. Although illustrated with reference to two stages **605i** and **605o**, it will be understood that multiple input or output transistor dies may be present on the attachment surface **101s**, with the output of one stage connected to the input of the next stage by respective IPDs **610**. The connections from the package leads **102g** and **102d** to the gate and drain contact pads **605p** of the dies **605i** and **605o** can be implemented by respective conductive wiring structures (illustrated as copper routing layers in RDL **614** in FIG. **6A** and/or as a wire-bonds **14** in FIG. **6B**), and/or by input/output impedance matching circuits and/or harmonic termination circuits (e.g., using integrated interconnects **110i/110o**) as described herein.

(59) FIG. **6C** is an equivalent circuit diagram representing the embodiments of FIGS. **6A** and **6B**. As shown in FIG. **6C**, the inter-stage matching network is implemented by capacitors **604** and passive device **610** to provide a shunt-L pre-matching network **Ls** at the output of the driver stage transistor die **605i** and at the input of the final stage transistor die **605o**, as well as a series L-C-L network that connects the driver and final stage transistor dies **605i** and **605o**. This topology may provide a broadband response for a multi-stage RF power amplifier product. It will be understood that the inter-stage impedance matching network between the transistor dies **605i** and **605o** shown in FIG. **6C** is by way of example only, and that inter-stage passive devices **610** that provide electrical connections between two or more active dies according to embodiments of the present disclosure may include or implement other network topologies.

(60) FIG. **7A** is a cross-sectional view illustrating an example of an integrated circuit device package including stacked topology structures in accordance with some embodiments of the present disclosure. As shown in FIG. **7A**, an RF power device package **700** includes active dies

**605i**, **605o** and an integrated interconnect (illustrated as an IPD or other passive device **610c**) assembled on a substrate **101**. As in FIG. 6A, the substrate **101** is implemented as a conductive structure **103** (e.g., a copper slug) that provides the attachment surface **101s**, the source lead **102s**, and thermal conductivity (e.g., a heat sink) for transmitting heat away from the transistors of the transistor dies **605i**, **605o**, and the active dies **605i**, **605o** define a multi-stage packaged RF power amplifier device. An inter-stage passive device **610c** is attached (illustrated as flip-chip mounted) to and provides electrical connections between bond pads **610p** thereof and bond pads **605p** of the two transistor dies **605i**, **605o**.

(61) In FIG. 7A, inter-stage matching capacitors **604** are not located beneath the inter-stage IPD **610c**, but rather, the capacitance is integrated into the IPD **610c**, e.g. as MIM capacitors. One or more conductive vias **610v** connect ends of the integrated capacitors to the package ground, e.g., as provided by the conductive structure **103**. In some embodiments, the conductive via(s) **610v** may be implemented by copper via(s) in a RDL. As such, the IPD **610c** includes the matching capacitance integrated therein to provide an inter-stage matching network that is configured to provide impedance matching between two or more amplifier stages implemented by the transistor dies **605i** and **605o**.

(62) FIG. 7B is an equivalent circuit diagram representing the embodiments of FIG. 7A. As shown in FIG. 7B, the inter-stage matching network is implemented by the passive device **610c** to provide a shunt-L pre-matching network  $L_s$  with a MIM or other integrated capacitor  $C$  at each of the output of the driver stage transistor die **605i** and the input of the final stage transistor die **605o**, as well as a series L-C-L network that connects the driver and final stage transistor dies **605i** and **605o**, similar to the embodiment of FIG. 6C.

(63) FIGS. 8A and 9A are cross-sectional views illustrating examples of sub-components of integrated circuit device packages including stacked topology structures in accordance with some embodiments of the present disclosure. As shown in FIGS. 8A and 9A, RF power device package **800** and **900** each include an active die **105** and an integrated interconnect (illustrated as an IPD or other passive device **110i**, **110c**) assembled on a package substrate **201**. The packages **800** and **900** include components and connections as in the embodiment shown in FIGS. 2A and 2B, with the substrate **201** implemented as a conductive structure **103** (e.g., a copper slug) that provides the attachment surface **201s**, the source lead **102s**, and thermal conductivity, and in some embodiments, a ground connection. The passive device **110i**, **110c** is provided only at the input side of the packages **800**, **900** to provide electrical connection between a conductive pad **105p** of the active die **105** and a gate lead **102g** of the package by solder bumps **111** without wire bonds therebetween. The passive device **110i**, **110c** (shown as a flip-chip IPD) implements an input pre-matching network for the transistor circuits implemented by the active die **105**, as in the embodiments of FIGS. 2A and 2B.

(64) In FIG. 8A, a capacitor chip **104** (e.g., MOS capacitors) for the input matching network is provided on the attachment surface **101s** adjacent the transistor die **105** and under the IPD **110i**. The bond pads **105p** and **104p** of the transistor die **105** and the capacitor chip **104** are connected to bond pads **110p** of the IPD **110i** by respective solder bumps **111**, without wire bonds therebetween.

(65) In FIG. 9A, the input capacitors are integrated into the flip-chip input IPD **110c**, e.g., as metal-insulator-metal (MIM) capacitors, and one or more conductive vias **110v** (e.g., copper via(s) in a RDL) are used to connect the integrated capacitor(s) to the package ground, e.g., as provided by the conductive structure **103**. In particular, one end of an integrated MIM cap may be connected to the electrical grounded copper slug **103** by copper vias **110v** or pillars built into the laminate around the die. The inductance needed for pre-matching or harmonic termination at the input side of the transistor die **105** can be partially or fully incorporated into the copper vias/pillars, to provide a high-Q, low loss inductance.

(66) In FIGS. 8A and 9A, the bond pads **110p** of the IPD **110i**, **110c** are connected directly to the gate lead **102g**, without conductive wiring structures therebetween. Likewise, the output of the

transistor die **105** may be connected directly to the drain lead **102d**. Both packages **800**, **900** can be used as a sub-component in a packaged RF power product by connecting the drain and gate lead **102d** and **102g** to the leads of the package with wire bonds, or copper routing in an RDL. The drain lead **102d** can also be connected to additional output pre-matching networks (e.g., by conductive wiring structures (such as copper routing in a RDL or wire bonds as shown in FIGS. 2A and 2B) or by IPDs as shown in FIGS. 1A and 1B) before connecting to the package output leads.

(67) FIGS. 8B and 9B are equivalent circuit diagrams representing the embodiments of FIGS. 8A and 9A, respectively. Similar to the embodiment of FIG. 2C, an arrangement of inductors L, Ls is implemented in the IPDs **110i**, **110c** to provide an impedance pre-matching network for the transistor arrangement of the active die **105**. In particular, the IPDs **110i**, **110c** and input capacitors (implemented by external capacitor chip **104** (e.g., MOS capacitors) in FIG. 8B; integrated capacitors C (e.g., MIM capacitors) in FIG. 9B) provide an L-C matching circuit (e.g., a low-pass L-C) at the fundamental frequency  $f_0$ , as well as a shunt-L inductance Ls matching circuit (e.g., a high-pass Ls) for optimum termination of one or more harmonic frequencies (e.g.,  $2f_0$ ). In FIG. 9B, the capacitance that may be needed for pre-matching and harmonic termination is integrated into the IPD **110c**.

(68) FIGS. 10A and 10B are plan and perspective views, respectively, illustrating examples of high-Q IPDs **110**, **610** that provide impedance matching and integrated interconnects in accordance with some embodiments of the present disclosure. In the examples of FIGS. 10A and 10B, the precise value of shunt-L inductance needed for appropriate pre-matching of the transistor is implemented using coil inductors Ls. The shape, width and general design of the coil inductors Ls may be optimized to reduce losses. One end of the coil inductors Ls end on a bump or contact pad **110pl**, which can be pre-attached with conductive bumps (e.g., **111**) for attachment to the capacitors (e.g., **104**) for pre-matching or high-density capacitors (e.g., **106**) for improving video band-width. The width of the series connection strip L used to implement the series inductors can be configured to provide the desired impedance transformation from the transistor die to the drain leads. The series connection strips L may extend between bump or contact pads **110p**, and can be treated as an extension of the board transmission line matching network, and width of each series connection strip L can be configured to provide the desired characteristic impedance. More generally, any of the passive devices described herein may include or may be implemented using series connection strips L that are coupled between contact pads **110p** to provide electrical connection between the contact pads **105p** of one or more active dies **105**, and/or between the contact pads **105p** an active die **105** and a package lead **102**, in addition to impedance transformation therebetween. Likewise, any of the passive devices described herein may include or may be implemented using coil inductors Ls configured for connections to capacitors (e.g., capacitors integrated therein or external capacitors by contact pads **110pl**).

(69) FIGS. 11 and 12 are cross-sectional views illustrating examples of thermally enhanced integrated circuit device packages including stacked topology structures in accordance with further embodiments of the present disclosure. The feature sizes in FIGS. 11 and 12 are exaggerated for ease of illustration. As shown in FIGS. 11 and 12, RF power device packages **1100**, **1200** include components **104**, **105**, **106**, **110** and connections similar to the packages **100a**, **100b**, and **100c** of FIGS. 1A, 1B, and 1C, but are mounted on a conductive base or flange **1101**, **1201** and protected by a lid member **1113**, **1213** of thermally enhanced packages, rather than a plastic over mold **113**. In particular, FIG. 11 illustrates a first implementation (referred to as a TEPAC package **1100**) and FIG. 12 illustrates a second implementation (referred to as a T3PAC package **1200**) of thermally enhanced packages in accordance with embodiments of the present disclosure.

(70) The TEPAC package **1100** of FIG. 11 may be a ceramic-based package that includes a base **1101** and an upper housing, which may include a lid member **1113** and sidewall members **1104**. The lid member **1113** and/or sidewalls **1104** may include ceramic materials (e.g., alumina) and may define an open cavity surrounding the components **104**, **105**, **106**, **110** on the conductive base or

flange **1101**. The conductive base or flange **1101** provides both an attachment surface **1101s** for the components **104**, **105**, **106**, **110**, as well as thermal conductivity (e.g., a heat sink) for dissipating or otherwise transmitting heat generated by the components outside of the package **1100**.

(71) The T3PAC package **1200** of FIG. **12** may also be a ceramic-based package that includes a base **1201** and an upper housing with a lid member **1213** and sidewall members **1204**. The lid member **1213** and sidewalls **1204** similarly define an open cavity surrounding the components **104**, **105**, **106**, **110** on the conductive base or flange **1201**, which likewise provides both an attachment surface **1201s** and thermal conductivity (e.g., a heat sink) for dissipating or otherwise transmitting heat outside of the package **1200**. In the package **1200**, the lid member **1213** may be a ceramic material (e.g., alumina), while the sidewall members **1204** are illustrated as printed circuit board (PCB).

(72) In FIGS. **11** and **12**, the flange **1101**, **1201** may be an electrically conductive material, for example, a copper layer/laminate or an alloy or metal-matrix composite thereof. In some embodiments, the flange **1101** may include a copper-molybdenum (CuMo) layer, CPC (Cu/MoCu/Cu), or other copper alloys, such as copper-tungsten CuW, and/or other laminate/multi-layer structures. In the example of FIG. **11**, the flange **1101** is illustrated as a CPC-based structure to which the sidewalls **1104** and/or lid member **1113** are attached. In the example of FIG. **12**, the flange **1201** is illustrated as a copper-molybdenum (RCM60)-based structure to which the sidewalls **1204** and/or lid member **1213** are attached, e.g., by a conductive glue **1208**.

(73) In FIGS. **11** and **12**, the active die **105**, passive devices (e.g., capacitor chips **104** and **106**), and integrated interconnects (collectively **110**) are attached to the attachment surface **1101s**, **1201s** of the flange **1101**, **1201** by respective conductive die attach material layers **107**. The flange **1101**, **1201** also provides the source lead **102s** for the package **1100**, **1200**. The gate lead **102g** and drain lead **102d** are provided by respective conductive wiring structures **1114**, **1214**, which are attached to the flange **1101**, **1201** and supported by the respective sidewall members **1104**, **1204**.

(74) The thicknesses of the sidewall members **1104**, **1204**, may result in a height differential between the components **104**, **105**, **106**, **110** and the package leads **102g**, **102d** relative to the attachment surface **1101s**, **1201s**. For example, the combined height of the active die **105** and the integrated interconnects **110i**, **110o** thereon may be about 100  $\mu\text{m}$  relative to the attachment surface **1101s**, while the gate and drain leads **102g** and **102d** may be separated from the attachment surface **1101s** by a distance of about 635  $\mu\text{m}$ . In the examples of FIGS. **11** and **12**, respective wire bonds **14** are thus used to connect the package leads **102g**, **102d** to contact pads **104p**, **106p** of the passive RF components **104**, **106** on the attachment surface **1101s**, **1201s**. As such, an RF signal input on a the lead **102g** may be passed through the wire bond **14** to input matching circuits **110i**, **104** and to a gate terminal **105p** of the RF transistor amplifier die **105**, and the amplified output RF signal may be passed from the drain terminal **105p** of the RF transistor amplifier die **105** to the output matching circuits **110o**, **106** and from there to the bond wire **14** for output through lead **102d**. It will be appreciated, however, that the wire bonds **14** may be omitted in other embodiments and different electrical connections may be used.

(75) Integrated circuit device packages including stacked topology structures in accordance with embodiments of the present disclosure may provide further advantages in that the stacked interconnection structures may allow for thinner or reduced-height packages in comparison to some conventional designs. In over mold package embodiments (e.g., as shown in FIGS. **1-9**), the routing of the package leads at the bottom of the package may also allow for packaging flexibility. For example, changes in height and/or spacing of the package leads can be accommodated by modifying the layout of the traces on the circuit board/PCB based on the modified package footprint. Thermally-enhanced package embodiments (e.g., as shown in FIGS. **11-12**) may offer similar advantages, but may require changes to the package dimensions (e.g., flange height and/or package lead spacing) relative to standardized dimensions.

(76) Accordingly, in embodiments of the present disclosure, electrical connections between

components (e.g., between circuit-level components, such as between the contact pads of one or more active transistor dies, and/or between the contact pads of active transistor dies and the gate and/or drain leads of the package) are implemented by one or more integrated interconnect structures (e.g., conductive wiring structures and/or passive devices, such as IPDs) physically extending between the components, rather than by wirebonds. That is, the integrated interconnects may provide both an interconnection and an impedance matching/harmonic termination function, such that the use of wirebonds in the package can be reduced or eliminated.

(77) As described herein, some embodiments of the present disclosure use high-Q IPDs ‘flipped over’ on top of the transistor and capacitors. The extra elevation of the IPD above the ground plane (e.g., as provided by conductive structures that may also define the attachment surface for the active dies) of the package leads to higher Q, and lower loss pre-match. The majority of the space beneath the flipped IPD can be used for capacitors, such as the high-density capacitors typically used on the output. Larger value capacitance can be used in the available space, thus improving the video-bandwidth of the device. To connect the RF signal from the IPD back to the RDL and gate/drain leads, a copper shim or IPD with TSVs can be used. The top of MOS capacitors and transistor die can be aligned to the same height by grinding the wafers (die or capacitors) to similar heights, or by using pre-form of different thickness to align the heights. The IPDs can be configured for both pre-matching of the fundamental frequency as well as optimum termination of one or more harmonic frequencies.

(78) The transistor dies (e.g., **105**) are illustrated herein in cross section, with reference to examples in which the gate and drain pads (e.g., **105p**) are on a top side/upper surface and a source pad is on a bottom side/lower surface of the semiconductor layer structure. In some embodiments, a top side metallization structure of the transistor dies may include a plurality of gate, drain, and/or source ‘fingers’, which may be connected by one or more respective buses.

(79) FIG. **13** is a sectional view that is taken through a portion of the top side metallization structure of the die **105**, along line A-A’ of FIG. **1A**. As shown in FIG. **13**, the transistor die **105** includes a semiconductor layer structure **130** with plurality of unit cell transistors **116** provided in an upper portion of the semiconductor layer structure **130**. Gate fingers **152**, drain fingers **154**, and source fingers **156** (and connecting buses) may define part of gate-, drain-, and source-connected electrodes of the die **105**, respectively. The gate fingers **152** may be formed of materials that are capable of making a Schottky contact to a Group III nitride-based semiconductor material, such as Ni, Pt, Cu, Pd, Cr, W and/or WSiN. The drain fingers **154** and/or source fingers **156** may include a metal, such as TiAlN, that can form an ohmic contact to Group III nitride-based materials. The gate fingers **152** may be electrically connected to each other by a gate bus **146**, and the drain fingers **154** may be electrically connected to each other by a drain bus **148**. One or more dielectric layers that help isolate the gate-, drain-, and source-connected structures from each other are not shown to better illustrate the elements.

(80) One of the unit cell transistors **116** is also shown in FIG. **13**. As shown, the unit cell transistor **116** includes a gate finger **152**, a drain finger **154** and a source finger **156** along with the underlying portion of the semiconductor layer structure **130**. Since the gate fingers **152** are electrically connected to a common gate bus **146**, the drain fingers **154** are electrically connected to a common drain bus **148**, and the source fingers **156** are electrically connected together via the conductive source vias **166** and the source pad, it can be seen that the unit cell transistors **116** are all electrically connected together in parallel.

(81) Embodiments of the present disclosure can be built on substrate or laminate (e.g., a redistribution layer (RDL) laminate), and assembled in batches using modern enhanced wafer level packaging techniques. Multiple parts can be built at once, reducing assembly time, cost, and yield issues. In addition, the wire-bonding process may be reduced or eliminated, saving time and cost. Heat generated by the transistor die can be removed effectively and conducted outside the package to a heat sink, for example, using a high-density copper filled array or embedded copper slug to

effectively remove the heat (as typical hollow or partially filled vias will not remove the heat effectively enough for high power RF applications). Embodiments of the present disclosure may be used in various cellular infrastructure (CIBR) RF power products (including, but not limited to 5 W, 10 W, 20 W, 40 W, 60 W, 80 W and different frequency bands) e.g., for 5G and base station applications. Embodiments of the present disclosure may also be applied to radar and monolithic microwave integrated circuit (MMIC)-type applications.

(82) Various embodiments have been described herein with reference to the accompanying drawings in which example embodiments are shown. These embodiments may, however, be embodied in different forms and should not be construed as limited to the embodiments set forth herein. Rather, these embodiments are provided so that this disclosure is thorough and complete and fully conveys the inventive concept to those skilled in the art. Various modifications to the example embodiments and the generic principles and features described herein will be readily apparent. In the drawings, the sizes and relative sizes of layers and regions are not shown to scale, and in some instances may be exaggerated for clarity.

(83) It will be understood that, although the terms “first,” “second,” etc. may be used herein to describe various elements, these elements should not be limited by these terms. These terms are only used to distinguish one element from another. For example, a first element could be termed a second element, and, similarly, a second element could be termed a first element, without departing from the scope of the present invention. As used herein, the term “and/or” includes any and all combinations of one or more of the associated listed items.

(84) The terminology used herein is for the purpose of describing particular embodiments only and is not intended to be limiting of the invention. As used herein, the singular forms “a,” “an” and “the” are intended to include the plural forms as well, unless the context clearly indicates otherwise. It will be further understood that the terms “comprises” “comprising,” “includes” and/or “including” when used herein, specify the presence of stated features, integers, steps, operations, elements, and/or components, but do not preclude the presence or addition of one or more other features, integers, steps, operations, elements, components, and/or groups thereof.

(85) Unless otherwise defined, all terms (including technical and scientific terms) used herein have the same meaning as commonly understood by one of ordinary skill in the art to which this invention belongs. It will be further understood that terms used herein should be interpreted as having a meaning that is consistent with their meaning in the context of this specification and the relevant art and will not be interpreted in an idealized or overly formal sense unless expressly so defined herein.

(86) It will be understood that when an element such as a layer, region, or substrate is referred to as being “on,” “attached,” or extending “onto” another element, it can be directly on the other element or intervening elements may also be present. In contrast, when an element is referred to as being “directly on” or “directly attached” or extending “directly onto” another element, there are no intervening elements present. It will also be understood that when an element is referred to as being “connected” or “coupled” to another element, it can be directly connected or coupled to the other element or intervening elements may be present. In contrast, when an element is referred to as being “directly connected” or “directly coupled” to another element, there are no intervening elements present.

(87) Relative terms such as “below” or “above” or “upper” or “lower” or “horizontal” or “lateral” or “vertical” may be used herein to describe a relationship of one element, layer or region to another element, layer or region as illustrated in the figures. It will be understood that these terms are intended to encompass different orientations of the device in addition to the orientation depicted in the figures.

(88) Embodiments of the invention are described herein with reference to cross-section illustrations that are schematic illustrations of idealized embodiments (and intermediate structures) of the invention. The thickness of layers and regions in the drawings may be exaggerated for clarity.

Additionally, variations from the shapes of the illustrations as a result, for example, of manufacturing techniques and/or tolerances, are to be expected. Thus, embodiments of the invention should not be construed as limited to the particular shapes of regions illustrated herein but are to include deviations in shapes that result, for example, from manufacturing. Elements illustrated by dotted lines may be optional in the embodiments illustrated.

(89) Like numbers refer to like elements throughout. Thus, the same or similar numbers may be described with reference to other drawings even if they are neither mentioned nor described in the corresponding drawing. Also, elements that are not denoted by reference numbers may be described with reference to other drawings.

(90) In the drawings and specification, there have been disclosed typical embodiments of the invention and, although specific terms are employed, they are used in a generic and descriptive sense only and not for purposes of limitation, the scope of the invention being set forth in the following claims.

## Claims

1. An integrated circuit device package, comprising: a substrate; a first die comprising active electronic components attached to the substrate; and at least one integrated interconnect structure on the first die opposite the substrate and comprising at least a portion of an input or output impedance matching network or harmonic termination between a circuit defined by the active electronic components of the first die and at least one package lead, the at least one integrated interconnect structure extending from the first die to the at least one package lead and providing electrical connection therebetween, wherein the at least one integrated interconnect structure is spaced apart from the first die opposite the substrate.
2. The integrated circuit device package of claim 1, wherein the electrical connection is free of a wire bond in the integrated circuit device package.
3. The integrated circuit device package of claim 1, wherein: the first die comprises a first bond pad, which is electrically connected to one or more of the active electronic components, on a surface of the first die opposite the substrate; and the at least one integrated interconnect structure comprises a contact pad that is on the first bond pad.
4. The integrated circuit device package of claim 3, wherein the at least one integrated interconnect structure comprises a conductive wiring pattern on a redistribution layer.
5. The integrated circuit device package of claim 3, wherein the at least one integrated interconnect structure comprises at least a portion of the input or output impedance matching network for the circuit defined by the active electronic components of the first die.
6. The integrated circuit device package of claim 5, wherein the at least one integrated interconnect structure comprises a passive device comprising one or more passive electronic components.
7. The integrated circuit device package of claim 6, wherein the contact pad is a second bond pad, which is electrically connected to the one or more passive electronic components, on a surface of the passive device that is facing the surface of the first die, wherein the second bond pad is connected to the first bond pad by a conductive bump therebetween such that the surface of the passive device is separated from the surface of the first die.
8. The integrated circuit device package of claim 6, wherein the active electronic components of the first die define a first radio frequency (RF) amplifier circuit, wherein an adjacent die comprises active electronic components that define a second RF amplifier circuit, and wherein the first and second RF amplifier circuits are connected in a multi-stage amplifier arrangement.
9. The integrated circuit device package of claim 6, wherein the passive device comprises an integrated passive device (IPD) including at least one inductor and is free of active electronic components.
10. The integrated circuit device package of claim 9, wherein the IPD comprises an insulating

material between conductive elements thereof to define at least one capacitor integrated therein.

11. The integrated circuit device package of claim 3, wherein: an adjacent die comprises one or more capacitors and at least one capacitor bond pad that is on a surface of the adjacent die opposite the substrate; the contact pad of the at least one integrated interconnect structure is a first contact pad; and the at least one integrated interconnect structure further comprises at least one second contact pad that is on the at least one capacitor bond pad.

12. The integrated circuit device package of claim 11, wherein the at least one package lead comprises a gate lead and the first bond pad is a gate pad, wherein the adjacent die is between the first die and the gate lead, and wherein the at least one integrated interconnect structure comprises the input impedance matching network for the circuit.

13. The integrated circuit device package of claim 11, wherein the at least one package lead comprises a drain lead and the first bond pad is a drain pad, wherein the adjacent die is between the first die and the drain lead, and wherein at least one integrated interconnect structure comprises the output impedance matching network for the circuit.

14. The integrated circuit device package of claim 1, wherein the active electronic components comprise power transistor devices, and wherein the first die comprises at least one of a Group III-nitride or silicon carbide.

15. A radio frequency (RF) power amplifier device package, comprising: a substrate; a first die, comprising a plurality of transistor cells, attached to the substrate at a source pad on a bottom surface thereof and comprising a gate or drain pad at a top surface thereof opposite the substrate; package leads configured to conduct electrical signals between the gate or drain pad of the first die and an external device; and an integrated interconnect structure on the first die and spaced apart therefrom opposite the substrate, the integrated interconnect structure comprising a first contact pad on the gate or drain pad, and a second contact pad coupled to one of the package leads, and wherein the integrated interconnect structure comprises at least a portion of an input or output impedance matching network between a circuit defined by the transistor cells of the first die and a package input or a package output provided by the one of the package leads.

16. The RF power amplifier device package of claim 15, wherein the integrated interconnect structure provides electrical connection from the gate or drain pad of the first die to the one of the package leads, wherein the electrical connection is free of a wire bond in the RF power amplifier device package.

17. The RF power amplifier device package of claim 15, wherein the integrated interconnect structure comprises a conductive wiring pattern on a redistribution layer or a passive device comprising one or more passive electronic components.

18. The RF power amplifier device package of claim 17, wherein the first contact pad is a bond pad, which is electrically connected to the one or more passive electronic components, on a surface of the passive device that is facing the top surface of the first die, wherein the bond pad is connected to the gate or drain pad by a conductive bump therebetween such that the surface of the passive device is separated from the top surface of the first die.

19. The RF power amplifier device package of claim 17, wherein the integrated interconnect structure further comprises a third contact pad coupled to an adjacent die, wherein the adjacent die comprises at least one bond pad on a surface thereof opposite the substrate and the third contact pad is on the at least one bond pad, and wherein: the adjacent die comprises one or more capacitors; or the adjacent die comprises a plurality of transistor cells that define a stage of an RF amplifier circuit.

20. The RF power amplifier device package of claim 15, wherein the first die comprises the gate pad and the drain pad at the top surface thereof.

21. The RF power amplifier device package of claim 15, wherein the integrated interconnect structure further comprises one or more inductors and a third contact pad, and further comprising: a second die comprising one or more capacitors attached to the substrate adjacent the first die, and a



bond pad on a surface thereof opposite the substrate, wherein the integrated interconnect structure is stacked on the second die such that the third contact pad is on the bond pad and the second contact pad is on the one of the package leads.

22. The RF power amplifier device package of claim 21, wherein the substrate is configured to provide an electrical ground, and wherein a distance between the integrated interconnect structure and the substrate is configured such that a quality factor of the one or more inductors is substantially maintained.

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